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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**LISTING OF CLAIMS:**

Claim 1 (original): A method of manufacturing a surface acoustic wave apparatus, comprising the steps of:

- preparing a piezoelectric substrate;
- forming a first electrode layer of an electrode pad on the piezoelectric substrate;
- forming at least one electrode for a surface acoustic wave element after the step of forming the first electrode layer;
- forming a second electrode layer of the electrode pad after the step of forming the electrode for the surface acoustic wave element; and
- forming a wiring electrode for electrically connecting the electrode pad and the electrode for the surface acoustic wave element.

Claim 2 (original): The method according to Claim 1, wherein the wiring electrode is simultaneously formed with the second electrode layer.

Claim 3 (original): The method according to Claim 1, further comprising the step of forming an adhesive layer as a substrate prior to the formation of the wiring electrode and the second electrode layer, wherein the wiring electrode and the second electrode layer are made of one of Al and an Al alloy, and the adhesive layer is made of one of a metal or an alloy having an adhesion to the first electrode layer that is higher than that of the Al and the Al alloy.

Claim 4 (original): The method according to Claim 1, further comprising the step

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of performing etching in order to form stepwise end surfaces at joint portions, to be connected with the wiring electrode, of the electrode for the surface acoustic wave element and the electrode pad, after the step of forming the electrode for the surface acoustic wave element, wherein the wiring electrode for electrically connecting the electrode for the surface acoustic wave element and the first electrode layer of the electrode pad and the second electrode layer of the electrode pad are simultaneously formed from the same conductive film.

Claim 5 (original): The method according to Claim 1, wherein each of the electrode for the surface acoustic wave element and the first electrode layer of the electrode pad includes at least two end surfaces of the joint portion.

Claim 6 (original): The method according to Claim 1, wherein the electrode for the surface acoustic wave element to be connected with the electrode pad is formed such that the end surface of the electrode for the surface acoustic wave element is in contact with the first electrode layer of the electrode pad in the step of forming the electrode for the surface acoustic wave element.

Claim 7 (original): The method according to Claim 1, wherein a particle diameter of a conductive particle in the conductive film constituting the wiring electrodes and the second electrode layer is smaller than a particle diameter of a conductive particle in one of the electrode for the surface acoustic wave element and the first electrode layer, which has a smaller film thickness.

Claim 8 (original): The method according to Claim 1, wherein the electrode for the surface acoustic wave element is formed by a lift-off method and the first electrode layer of the electrode pad is formed by etching.

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Claim 9 (original): The method according to Claim 1, wherein at least one electrode for a second surface acoustic wave element that is different from the electrode for the surface acoustic wave element is simultaneously formed with the first electrode layer in the step of forming the first electrode layer.

Claims 10-22 (canceled).